

# Silizium-PIN-Fotodiode mit Tageslichtsperrfilter

## Silicon-PIN-Photodiode with Daylight Filter

### SFH 205 FA



#### Wesentliche Merkmale

- Speziell geeignet für Anwendungen bei 880 nm
- Kurze Schaltzeit (typ. 20 ns)
- 5 mm-Plastikbauform im LED-Gehäuse
- Auch gegurtet lieferbar

#### Anwendungen

- IR-Fernsteuerung von Fernseh- und Rundfunkgeräten, Videorecordern, Lichtdimmern, Gerätefernsteuerungen
- Lichtschranken für Gleich- und Wechsellichtbetrieb

Typ Type	Bestellnummer Ordering Code
SFH 205 FA	Q62702-P1677

#### Features

- Especially suitable for applications of 880 nm
- Short switching time (typ. 20 ns)
- 5 mm LED plastic package
- Also available on tape and reel

#### Applications

- IR-remote control of hi-fi and TV sets, video tape recorders, dimmers, remote control of various equipment
- Photointerrupters

**Grenzwerte**  
**Maximum Ratings**

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{op}; T_{stg}$	- 40 ... + 100	°C
Löttemperatur (Lötstelle 2 mm vom Gehäuse entfernt bei Lötzeit $t \leq 3$ s) Soldering temperature in 2 mm distance from case bottom ( $t \leq 3$ s)	$T_s$	230	°C
Sperrspannung Reverse voltage	$V_R$	32	V
Verlustleistung, $T_A = 25$ °C Power dissipation	$P_{tot}$	150	mW

**Kennwerte ( $T_A = 25$  °C,  $\lambda = 870$  nm)**
**Characteristics**

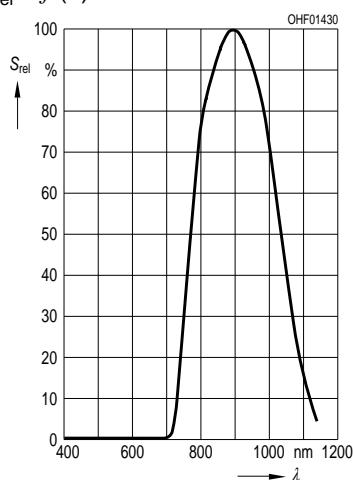
Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Fotostrom Photocurrent $V_R = 5$ V, $E_e = 1$ mW/cm <sup>2</sup>	$I_P$	60 ( $\geq 45$ )	µA
Wellenlänge der max. Fotoempfindlichkeit Wavelength of max. sensitivity	$\lambda_{S\ max}$	900	nm
Spektraler Bereich der Fotoempfindlichkeit $S = 10\%$ von $S_{max}$ Spectral range of sensitivity $S = 10\%$ of $S_{max}$	$\lambda$	740 ... 1100	nm
Bestrahlungsempfindliche Fläche Radiant sensitive area	A	7.00	mm <sup>2</sup>
Abmessungen der bestrahlungsempfindlichen Fläche Dimensions of radiant sensitive area	$L \times B$ $L \times W$	2.65 × 2.65	mm × mm
Abstand Chipoberfläche zu Gehäuseoberfläche Distance chip surface to case surface	H	2.3 ... 2.5	mm
Halbwinkel Half angle	φ	± 60	Grad deg.
Dunkelstrom, $V_R = 10$ V Dark current	$I_R$	2 ( $\leq 30$ )	nA

Kennwerte ( $T_A = 25^\circ\text{C}$ ,  $\lambda = 870 \text{ nm}$ )

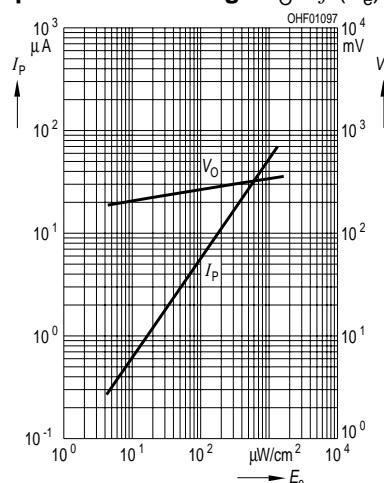
Characteristics (cont'd)

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Spektrale Fotoempfindlichkeit Spectral sensitivity	$S_\lambda$	0.63	$\text{A}/\text{W}$
Quantenausbeute Quantum yield	$\eta$	0.9	Electrons Photon
Leerlaufspannung, $E_e = 1 \text{ mW/cm}^2$ Open-circuit voltage	$V_O$	350 ( $\geq 280$ )	$\text{mV}$
Kurzschlußstrom, $E_e = 1 \text{ mW/cm}^2$ Short-circuit current	$I_{SC}$	56	$\mu\text{A}$
Anstiegs- und Abfallzeit des Fotostromes Rise and fall time of the photocurrent $R_L = 50 \Omega$ ; $V_R = 5 \text{ V}$ ; $\lambda = 850 \text{ nm}$ ; $I_p = 800 \mu\text{A}$	$t_r, t_f$	20	ns
Durchlaßspannung, $I_F = 100 \text{ mA}$ , $E = 0$ Forward voltage	$V_F$	1.3	V
Kapazität, $V_R = 0 \text{ V}$ , $f = 1 \text{ MHz}$ , $E = 0$ Capacitance	$C_0$	72	pF
Temperaturkoeffizient von $V_O$ Temperature coefficient of $V_O$	$TC_V$	- 2.6	$\text{mV/K}$
Temperaturkoeffizient von $I_{SC}$ Temperature coefficient of $I_{SC}$	$TC_I$	0.03	%/K
Rauschäquivalente Strahlungsleistung Noise equivalent power $V_R = 10 \text{ V}$	NEP	$4.0 \times 10^{-14}$	$\frac{\text{W}}{\sqrt{\text{Hz}}}$
Nachweisgrenze, $V_R = 10 \text{ V}$ Detection limit	$D^*$	$6.6 \times 10^{12}$	$\frac{\text{cm} \times \sqrt{\text{Hz}}}{\text{W}}$

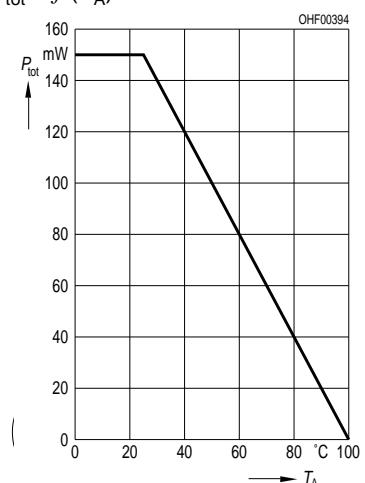
**Relative Spectral Sensitivity**  
 $S_{\text{rel}} = f(\lambda)$



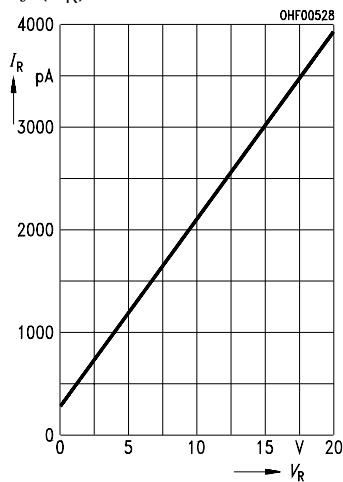
**Photocurrent  $I_P = f(E_e)$ ,  $V_R = 5 \text{ V}$**   
**Open-Circuit Voltage  $V_O = f(E_e)$**



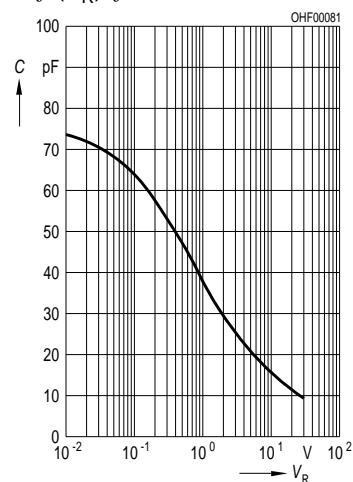
**Total Power Dissipation**  
 $P_{\text{tot}} = f(T_A)$



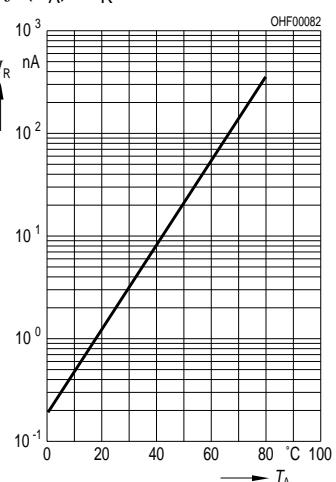
**Dark Current**  
 $I_R = f(V_R), E = 0$



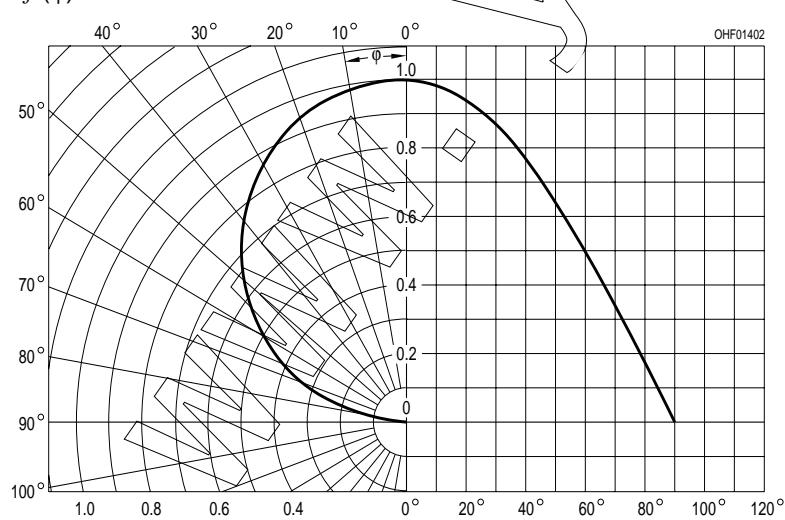
**Capacitance**  
 $C = f(V_R), f = 1 \text{ MHz}, E = 0$



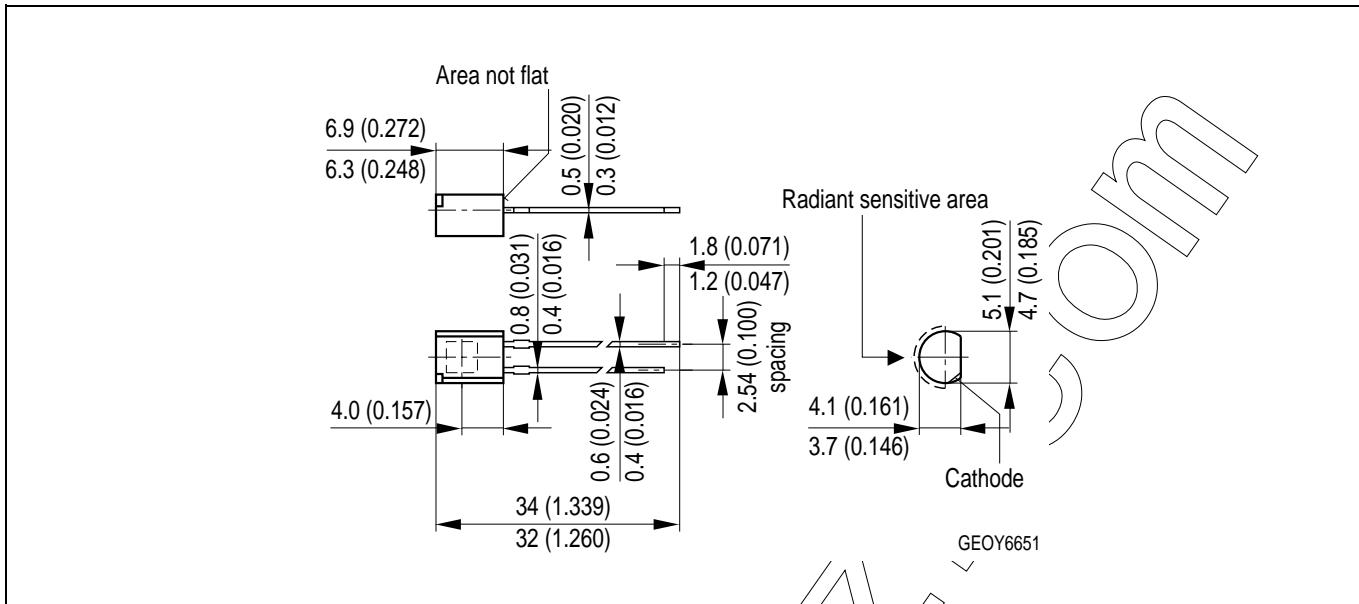
**Dark Current**  
 $I_R = f(T_A), V_R = 10 \text{ V}, E = 0$



**Directional Characteristics**  
 $S_{\text{rel}} = f(\phi)$



## Maßzeichnung Package Outlines



Maße werden wie folgt angegeben: mm (inch) / Dimensions are specified as follows: mm (inch).

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### Attention please!

The information describes the type of component and shall not be considered as assured characteristics.  
Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances. For information on the types in question please contact our Sales Organization.

### Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

**Components used in life-support devices or systems must be expressly authorized for such purpose!** Critical components<sup>1</sup>, may only be used in life-support devices or systems<sup>2</sup> with the express written approval of OSRAM OS.

<sup>1</sup> A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system.

<sup>2</sup> Life support devices or systems are intended (a) to be implanted in the human body, or (b) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered.